

MMB385B 3.7-4.0GHz MMB Series TDD BPF

Features

- Low Loss with High Rejection
- Universal footprint across family for all TDD bands

Applications

- Wireless Infrastructure applications
- High-performance carrier-grade TDD Pico-cells.

Description

Surface mount ceramic bandpass filter supports a universal footprint across all TDD frequency bands enabling the use of a common system PCB. Superior rejection, insertion loss, reliability, as well as both peak and average power handling compared to other bandpass filter technologies.

Electrical Specifications

Parameter	Frequency (MHz)	Typical at 25℃	Spec. at 25℃	Spec. over -40°C to +85°C
Nominal Impedance	-	50 ohms	-	-
Average Input Power	-	-	-	10.0 Watt max
Peak Input Power	-	-	-	100 Watt max
Input-Output Response				
Passband Insertion Loss (100 MHz avg)	3700-4000	1.4 dB	1.5 dB max	1.6 dB max
Passband Insertion Loss (20 MHz avg)	3700-4000	1.9 dB	2.0 dB max	2.1 dB max
Passband Insertion Loss (10 MHz avg)	3700-4000	2.0 dB	2.2 dB max	2.3 dB max
Passband Return Loss	3700-4000		13 dB min	12 dB min
Attenuation:	1-2495		67 dB min	67 dB min
	2496-2690		64 dB min	64 dB min
	2691-3400		40 dB min	40 dB min
	3401-3660		25 dB min	25 dB min
	3661-3677.5		9.5 dB min	8.0 dB min
	4022.5-4039		9.5 dB min	8.0 dB min
	4040-4399		25 dB min	25 dB min
	4400-5149		47 dB min	47 dB min
	5150-5950		40 dB min	40 dB min
	5951-7125		30 dB min	30 dB min
	7400-8000		No spec assured	No spec assured

Note: CTS tests each unit to the critical specifications above.	-
Subsequent audits may deviate due to repeatability among	In
different test systems which shall not exceed these allowances.	F

pecification	Allowance
sertion Loss	0.1 dB
Return Loss	1.0 dB
ttenuation	1.0 dB



RoH!

Connect

Part Dimensions: 40.0 × 6.0 × 9.3 mm • 6.13 g Materials: Ag plated ceramic block with tin plated brass shield

2022-03-22 Rev. B

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Mechanical Drawing

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Dim.	Nominal	Tolerance
	(mm)	(±mm or Max)
Α	40.0	max
В	4.4	max
С	1.0	0.13
D	0.5	0.13
E	0.5	0.13
F	4.5	0.25
G	31.0	0.13
Н	9.3	max
	1.0	0.13
J	1.4	0.2

Combined 40mm & 50mm universal footprint PCB lavout is also available.

IMPORTANT: Please assure >=30mils (0.75mm) thickness of dielectric beneath the I/O Pads <u>and</u> the surrounding clearance zone down to the ground plane.

Please assure sufficient ground vias between the top metal ground plane and the primary ground plane.

Recommended solder: 6 mils of SAC305 with reflow including 120s of soak at 217°C, and up to 30 sec peak at 241°C.



G

Packaging and Marking



40.3 mm

9.6 mm

16.0 mm



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6.1 mm

56.0 mm

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S11[dB](1) -0.285

S21[dB](1) -79.6

-2.31

-38.5

-4.17

-11.3

-17.2

-2.2

-19.3

-0.913

-18

-2.15

-2.6

-12

-1.11

-34.9

-0.399

-55.9

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Electrical Response